| © Copyright                            | <b>Composition D</b><br>t 2005. IPC, Bannoc<br>l and Pan-American                                     | cburn, Illinois. A           | ll rights reserved a tions. | under both           | This docume<br>level parts, t | ent is a declarat<br>he declaration e                             | ion of the su | ibstances v<br>s all lower  | within the manufactur<br>level materials for w | rer listed ite<br>hich the m | em. Note:<br>anufacture | if the item is an as<br>r has engineering | sembly with low responsibility. |  |
|--|---|------------------------------|-----------------------------|----------------------|-------------------------------|---|---------------|-----------------------------|--|------------------------------|-------------------------|---|---------------------------------|--|
|  | IPC Web Site for Information on IPC-1752 Standard Form Type<br>http://www.ipc.org/IPC-175x Distribute |                              |                             |                      | *                             | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materia |               |                             |  |                              | als and Mfg Information |   |                                 |  |
| Supplier Information                   |   |                              |                             |                      |                               |   |               |                             |  |                              |                         |   |                                 |  |
| Company name*                          | Company uni   | Company unique ID            |                             |                      | Unique ID Authority           |   |               |                             | Response Date*                                 |                              |                         |   |                                 |  |
| onsemi                                 |   |                              |                             |                      |                               |   |               |                             |  | 2025-05-11                   |                         |   |                                 |  |
| Contact Name Title -                   |   |                              | ïtle - Contact              |                      |                               | Phone - Contact*  |               |                             |  | Email - Contact*             |                         |   |                                 |  |
| Product-Env-Stewards                   | Product Envi  | Product Enviro Compliance    |                             |                      | NA                            |   |               |                             | Product-Env-Stewards@onsemi.com                |                              |                         |   |                                 |  |
| Authorized Representative* Tit         |   |                              | Title - Representative      |                      |                               | Phone - Representative*   |               |                             |  | Email - Representative*      |                         |   |                                 |  |
| Product-Env-Stewards                   | Product Envi  | Product Enviro Compliance    |                             |                      | NA                            |   |               |                             | Product-Env-Stewards@onsemi.com                |                              |                         |   |                                 |  |
| Requester Item Number                  | n Number Mfr Item N   |                              | Number Mfr Item Name        |                      |                               | Effective Date  | Version       | ion Manufacturing Site      |  | V                            | Veight*                 | UOM                                       | Unit Type                       |  |
|  | NVMF<br>T1G   | NVMFD6H840NLWF T8 80V LL SO8 |                             | FL DS                |                               | 2025-05-11  |               | N                           | MY1  |                              | 9.49                    | mg  | Each                            |  |
| Aanufacturing Proccess In              | formation   |                              |                             |                      |                               |   |               |                             |  |                              |                         |   |                                 |  |
| Terminal Plating / Grid A              | Terminal Plating / Grid Array Material Terminal Base A  |                              | Alloy                       | J-STD-020 MSL Rating |                               | Peak Process Body Temperature                                     |               | re Max Time at Peak Tempera |  | ire Num                      | ber of Reflow Cyc       | les                                       |                                 |  |
| Matte Tin (Sn) - annealed CU           |   | CU Alloy                     | 1                           |                      |                               | <b>260</b> C  |               | С                           | 30 seco  |                              | seconds 3               |   |                                 |  |
| omments                                |   |                              |                             |                      |                               |   |               |                             |  |                              |                         |   |                                 |  |
| vel 1 - maximum time at peak te        | mperature during s  | oldering is 10-3             | 0 seconds                   |                      |                               |   |               |                             |  |                              |                         |   |                                 |  |
| or more information regarding <b>n</b> | naterial compositio   | n please refer to            | page 3                      |                      |                               |   |               |                             |  |                              |                         |   |                                 |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *  | Detailed  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>iffies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the  | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst   | ances per the definition above except for sele   | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol   | der alloys containing 85% by weight or m   | ore lead).  |   |   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |   |  | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska  | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance               | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|-------------------------|------------------|--------|---------|-----------------|
| Clip                 | 0.34   | mg              | Supplier | Zinc (Zn)               | 7440-66-6        |        | 0.0004  | mg              |
|                      |        |                 | Supplier | Iron (Fe)               | 7439-89-6        |        | 0.008   | mg              |
|                      |        |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 0.3315  | mg              |
|                      |        |                 | Supplier | Phosphorus (P)          | 7723-14-0        |        | 0.0001  | mg              |
| Die                  | 0.36   | mg              | Supplier | Silicon (Si)            | 7440-21-3        |        | 0.36    | mg              |
| Die Attach Solder    | 0.82   | mg              | Supplier | Silver (Ag)             | 7440-22-4        |        | 0.0205  | mg              |
|                      |        |                 | А        | Lead (Pb)               | 7439-92-1        | 7a     | 0.7585  | mg              |
|                      |        |                 | Supplier | Tin (Sn)                | 7440-31-5        |        | 0.041   | mg              |
| Lead Frame           | 37.39  | mg              | Supplier | Silver (Ag)             | 7440-22-4        |        | 0.3739  | mg              |
|                      |        |                 | Supplier | Iron (Fe)               | 7439-89-6        |        | 0.0374  | mg              |
|                      |        |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 36.9675 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)          | 7723-14-0        |        | 0.0112  | mg              |
| Mold Compound-Black  | 48.93  | mg              |          | Epoxy resin             | proprietary data |        | 3.6698  | mg              |
|                      |        |                 | Supplier | Phenolic Resin          | Proprietary Data |        | 1.2233  | mg              |
|                      |        |                 | Supplier | Silica Amorphous (SiO2) | 7631-86-9        |        | 3.6698  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)        | 1333-86-4        |        | 0.2446  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)     | 60676-86-0       |        | 40.1226 | mg              |
| Plating              | 1.56   | mg              | Supplier | Tin (Sn)                | 7440-31-5        |        | 1.56    | mg              |
| Wire Bond - Cu       | 0.09   | mg              | Supplier | Copper (Cu)             | 7440-50-8        |        | 0.09    | mg              |